

Fig. 1A

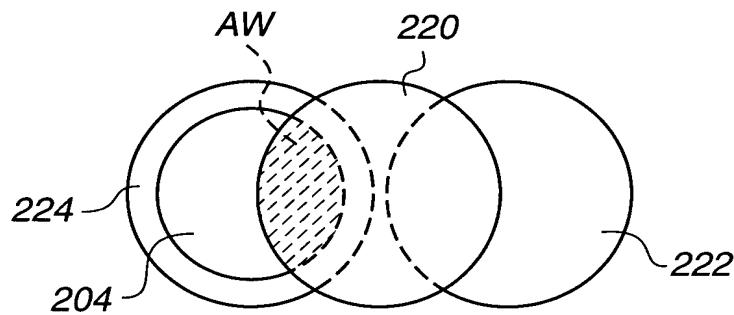
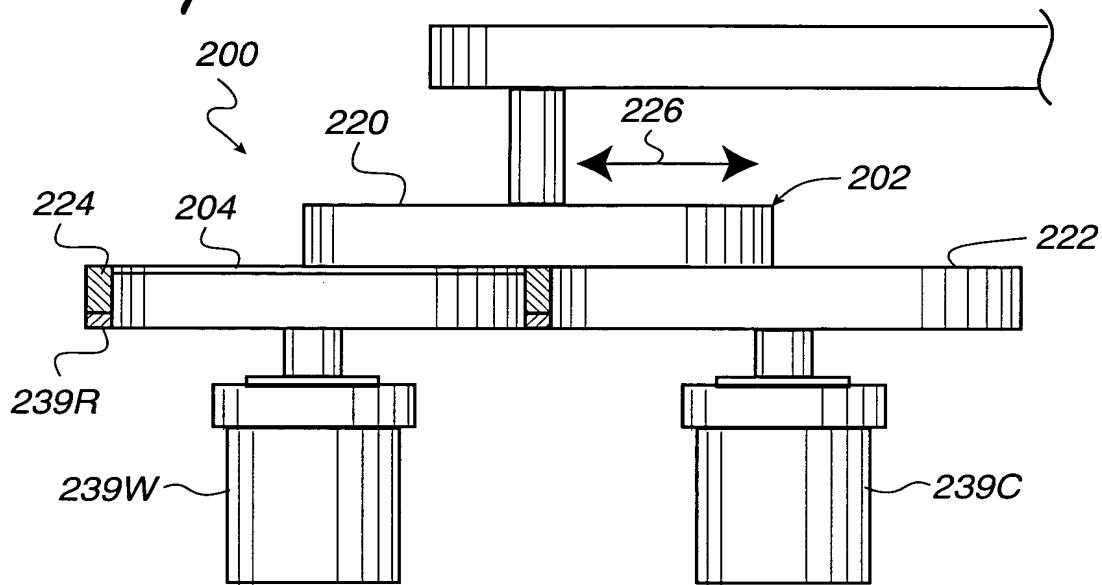


Fig. 1B

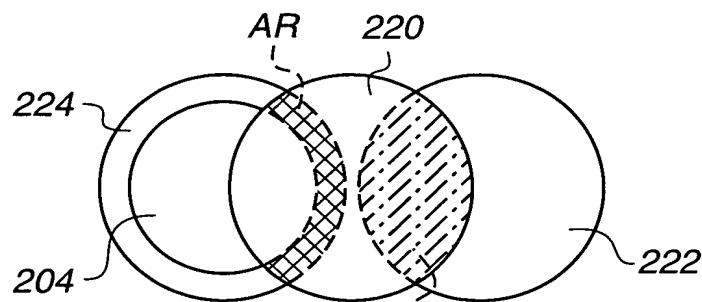
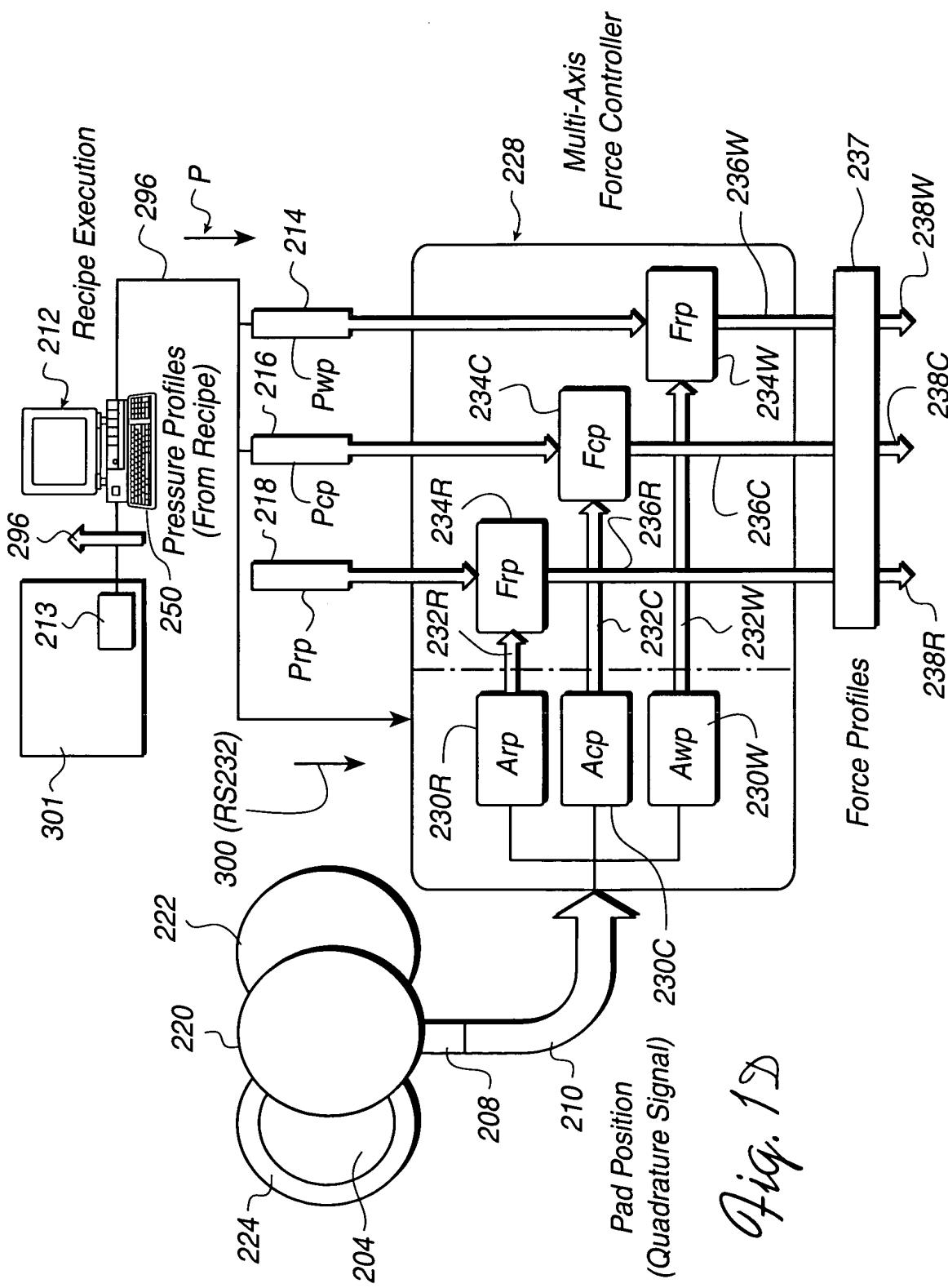


Fig. 1C

**Title: METHODS WITH RESOLUTION ENHANCEMENT FEATURE FOR
IMPROVING ACCURACY OF CONVERSION OF REQUIRED CHEMICAL MECHANICAL
POLISHING PRESSURE TO FORCE TO BE APPLIED BY POLISHING HEAD TO WAFER**



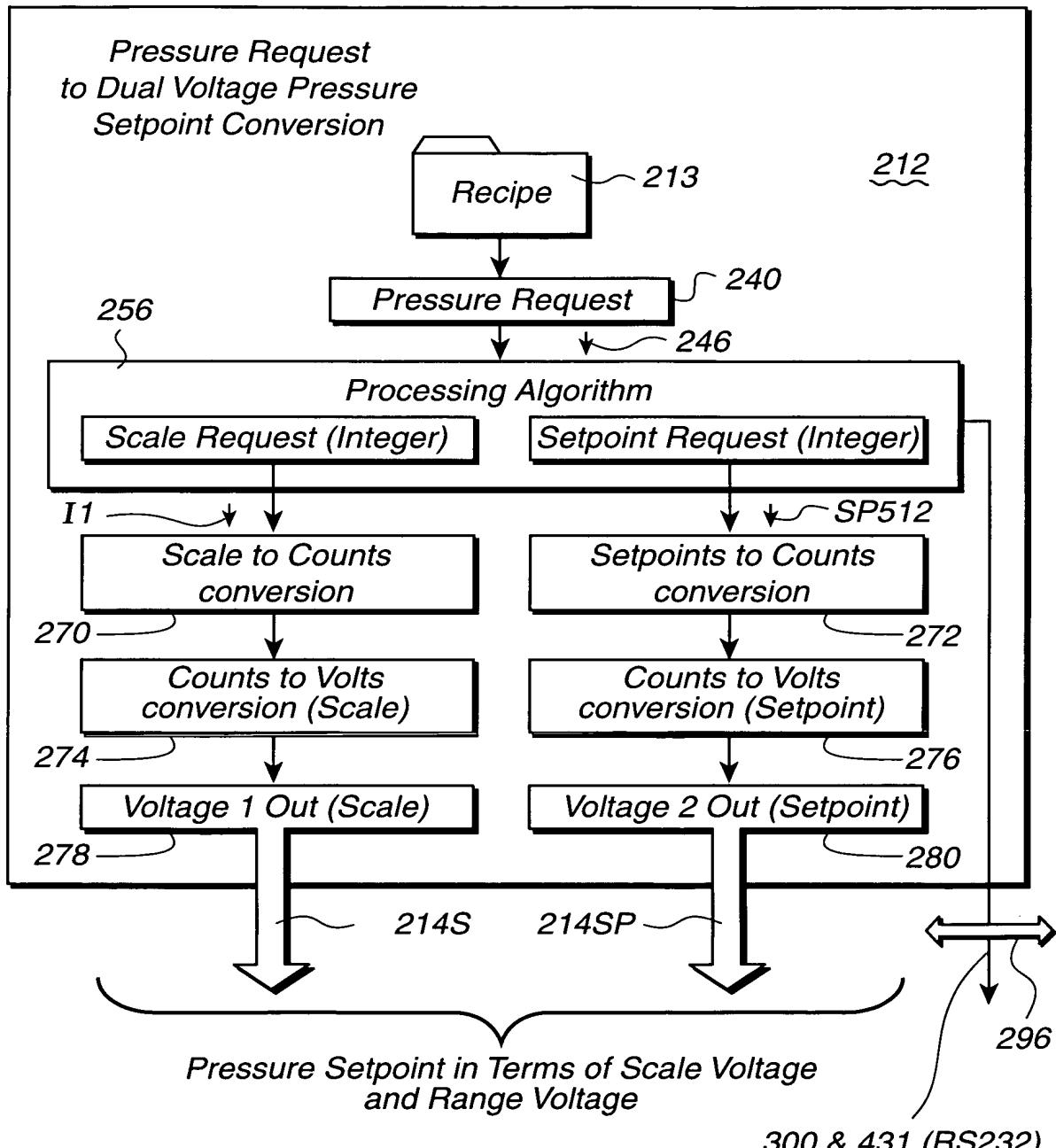


Fig. 2

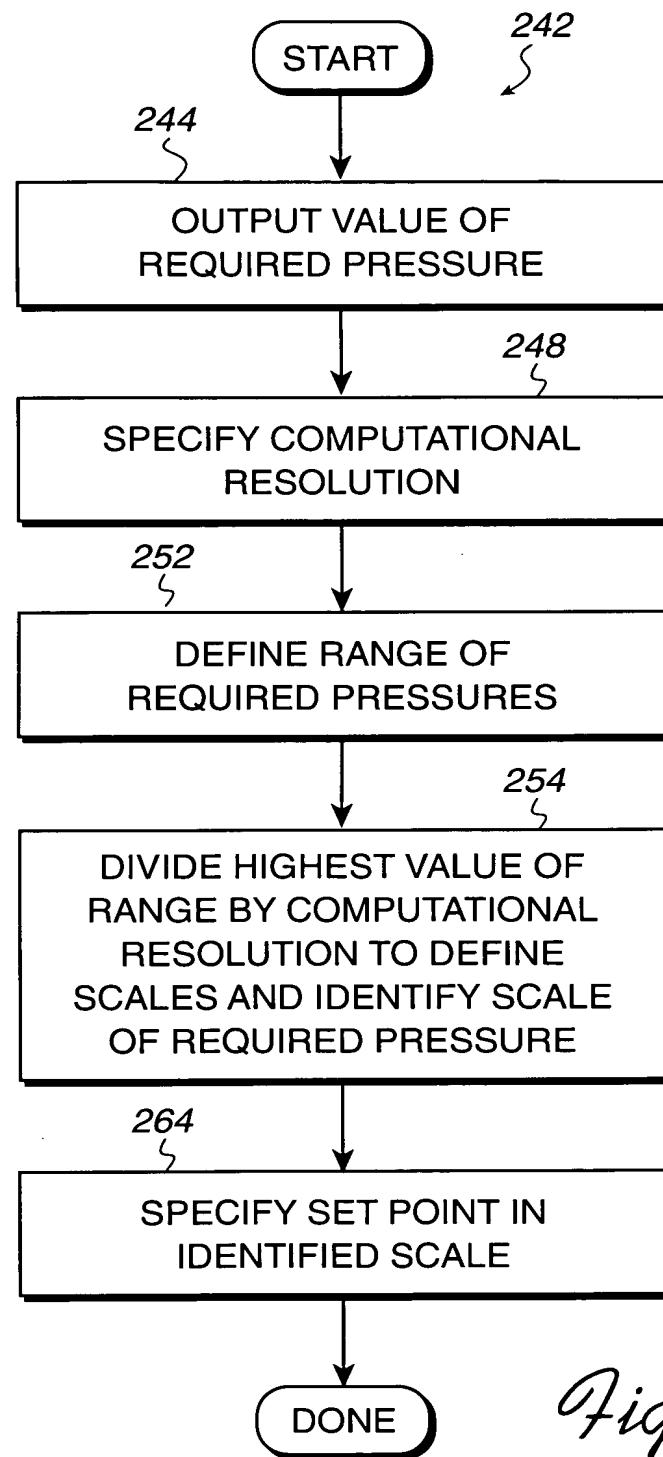


Fig. 3

Title: METHODS WITH RESOLUTION ENHANCEMENT FEATURE FOR
IMPROVING ACCURACY OF CONVERSION OF REQUIRED CHEMICAL MECHANICAL
POLISHING PRESSURE TO FORCE TO BE APPLIED BY POLISHING HEAD TO WAFER
Inventor: Miguel A. Saldana Docket No. LAM2P255D1 Filing Date: February 26, 2004

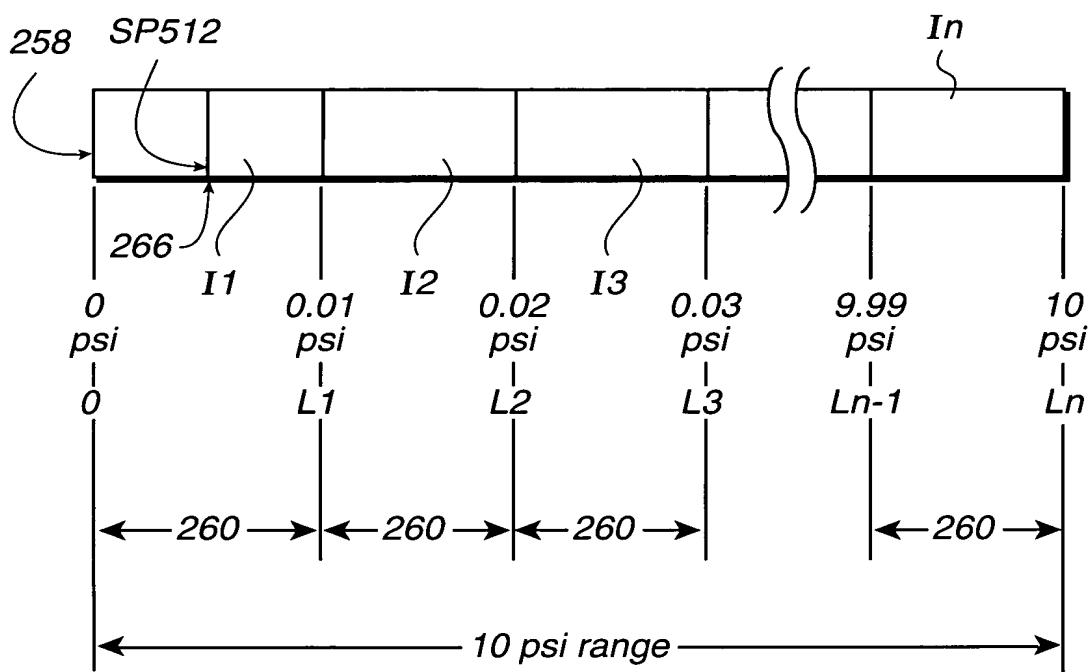


Fig. 4

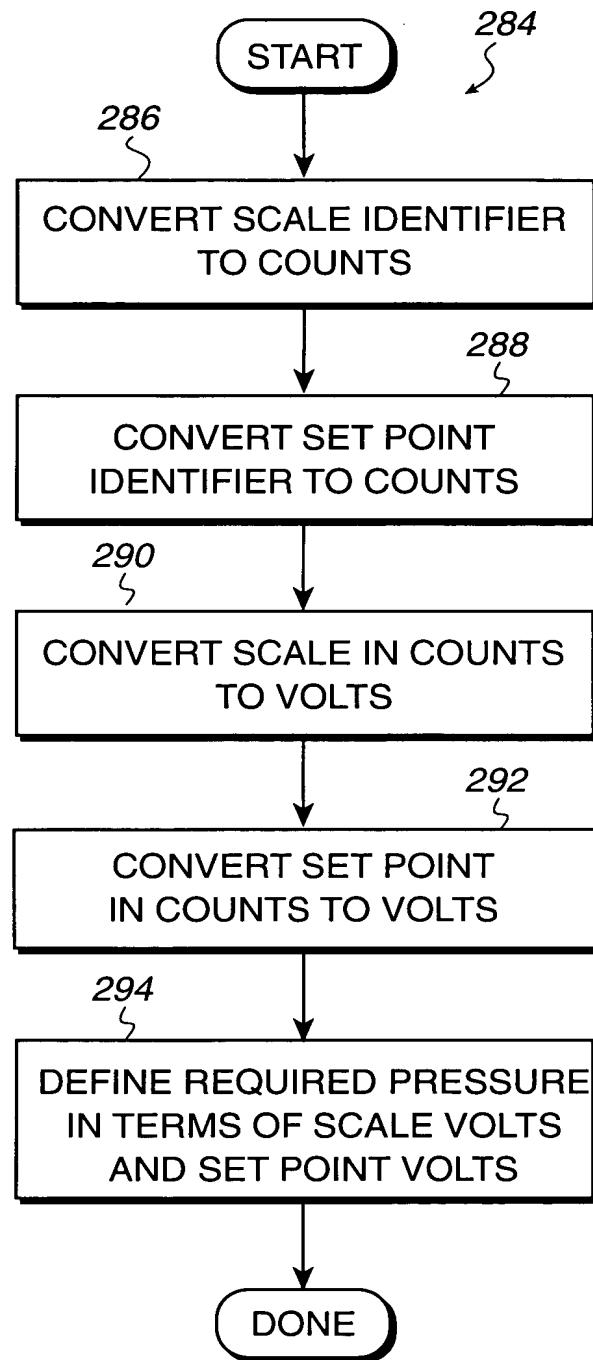


Fig. 5

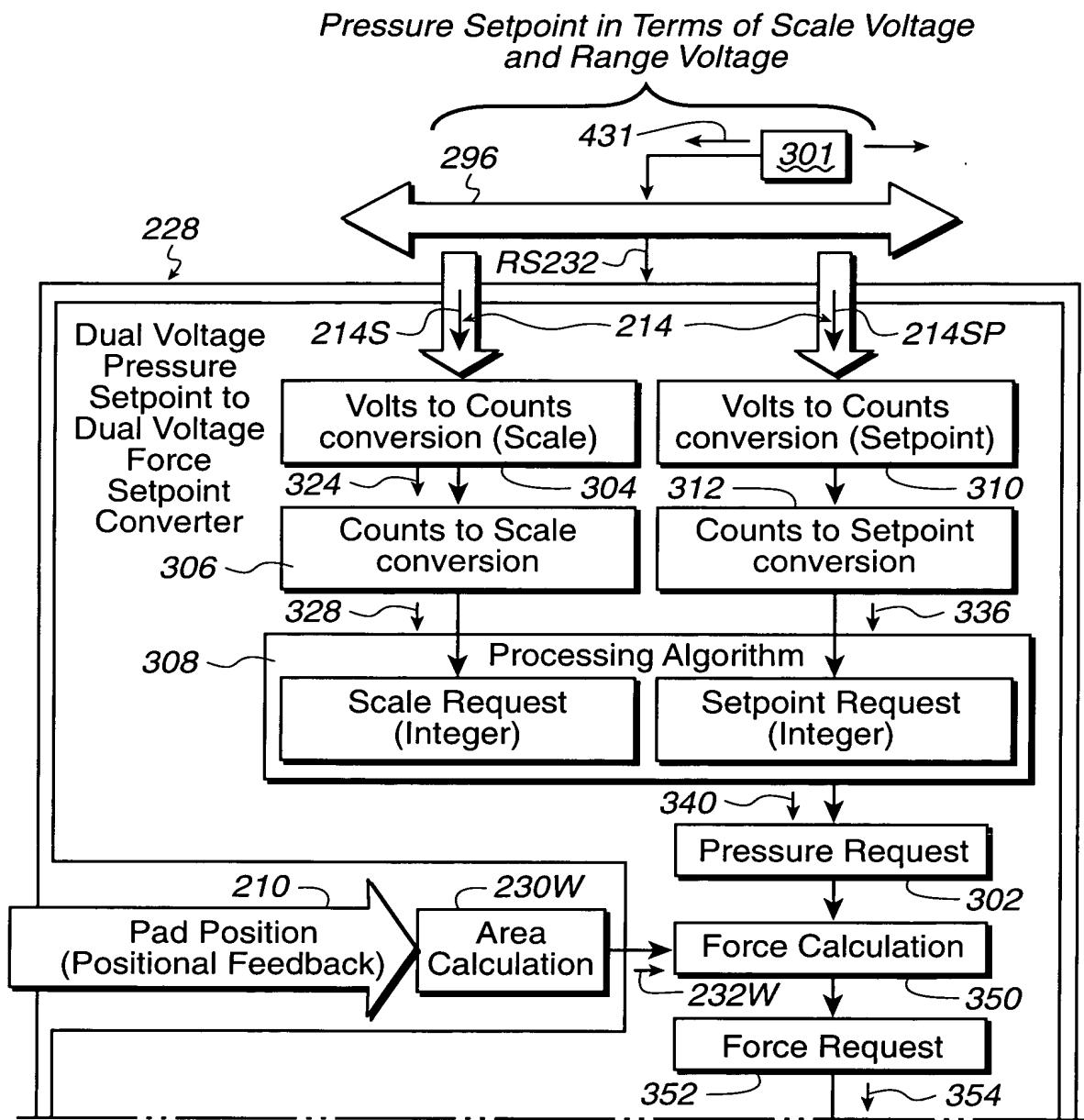


Fig. 6

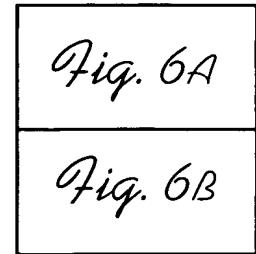


Fig. 6A

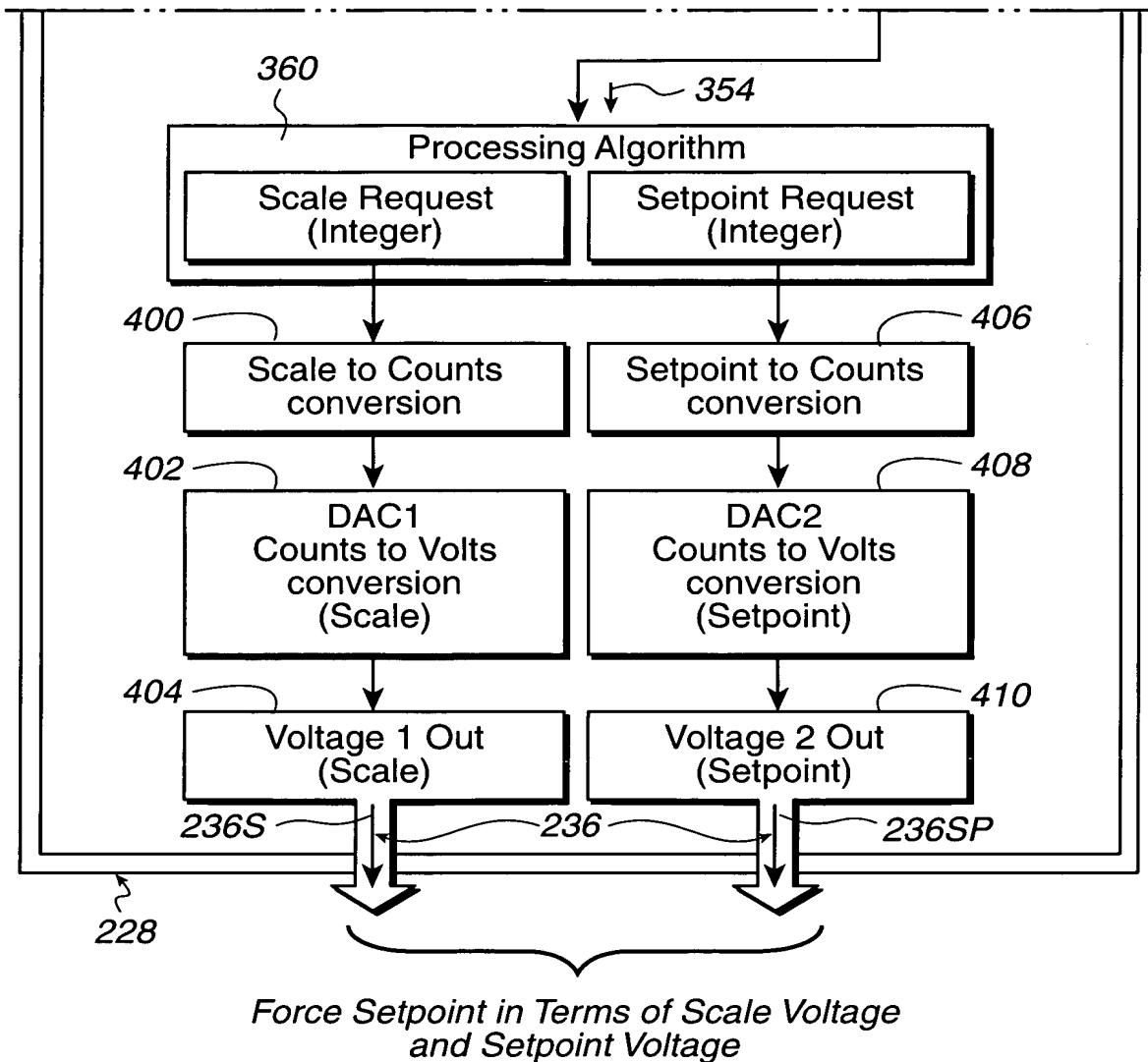


Fig. 6B

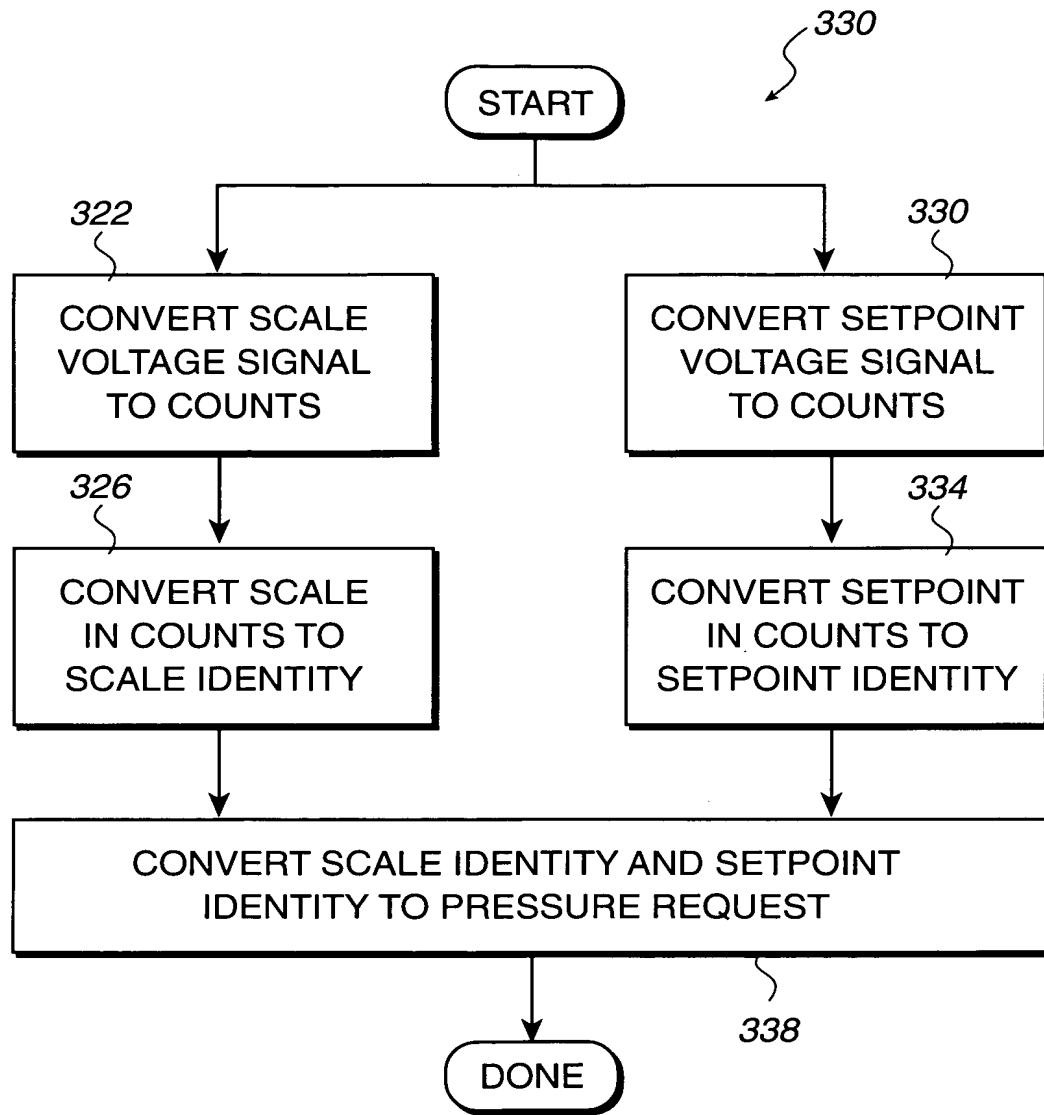


Fig. 7

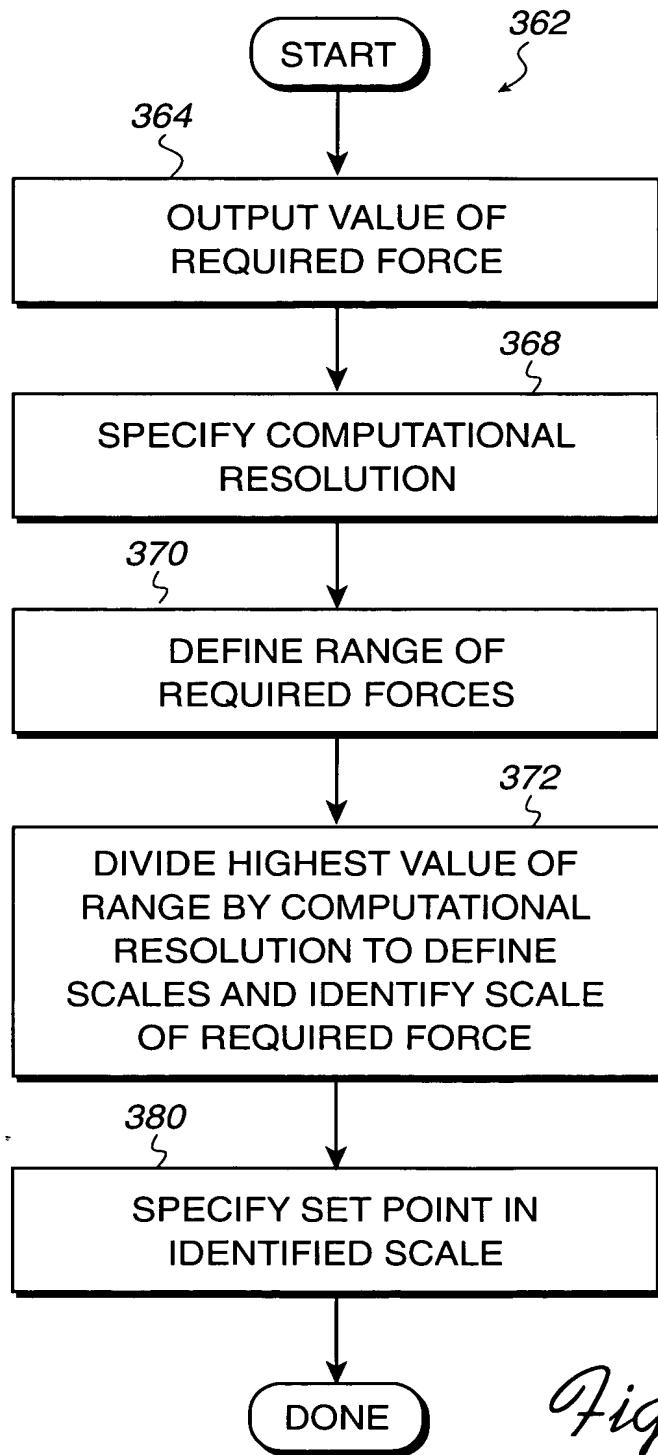


Fig. 8

Title: METHODS WITH RESOLUTION ENHANCEMENT FEATURE FOR
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Inventor: Miguel A. Saldana Docket No. LAM2P255D1 Filing Date: February 26, 2004

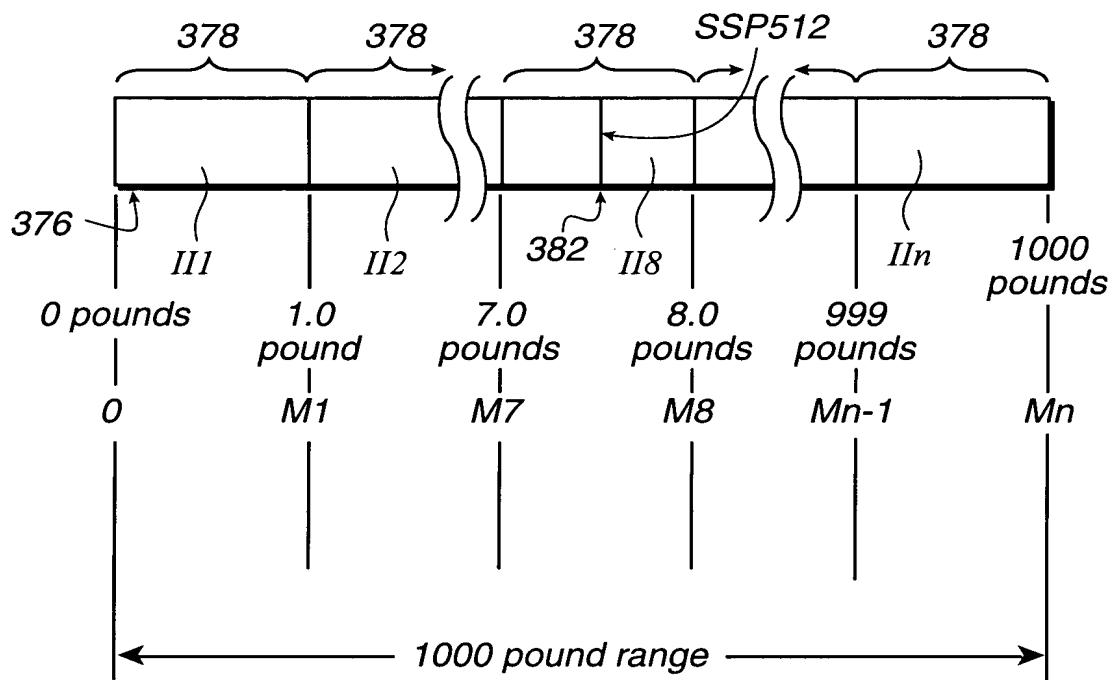


Fig. 9

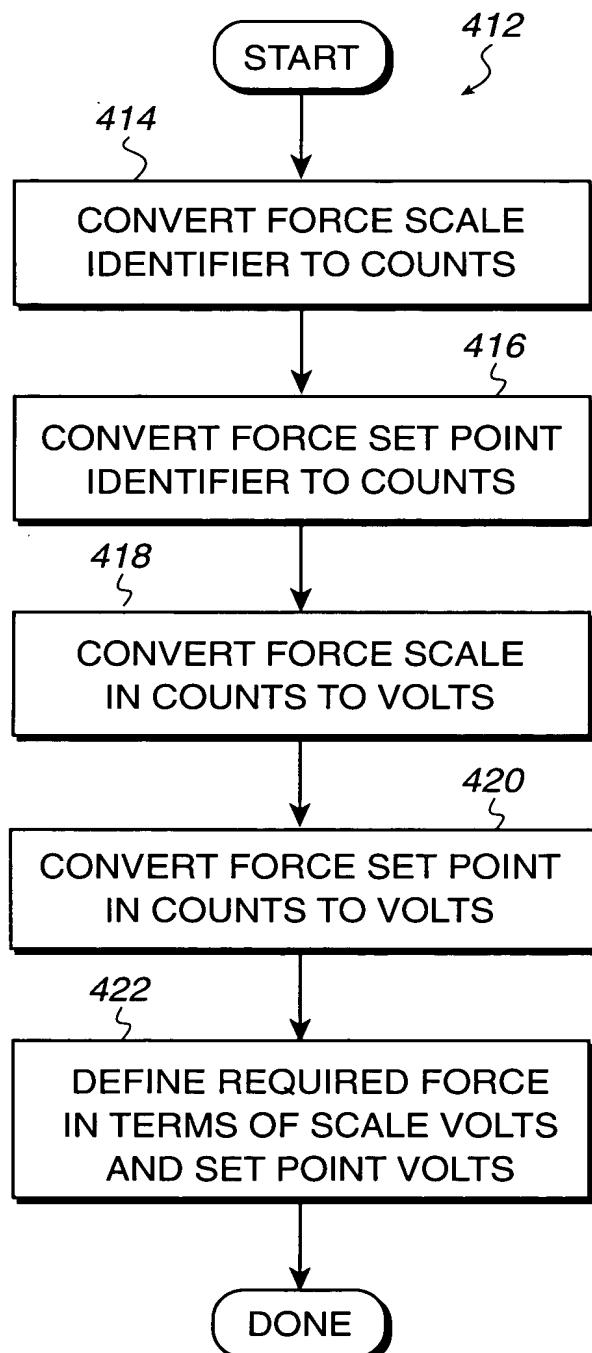
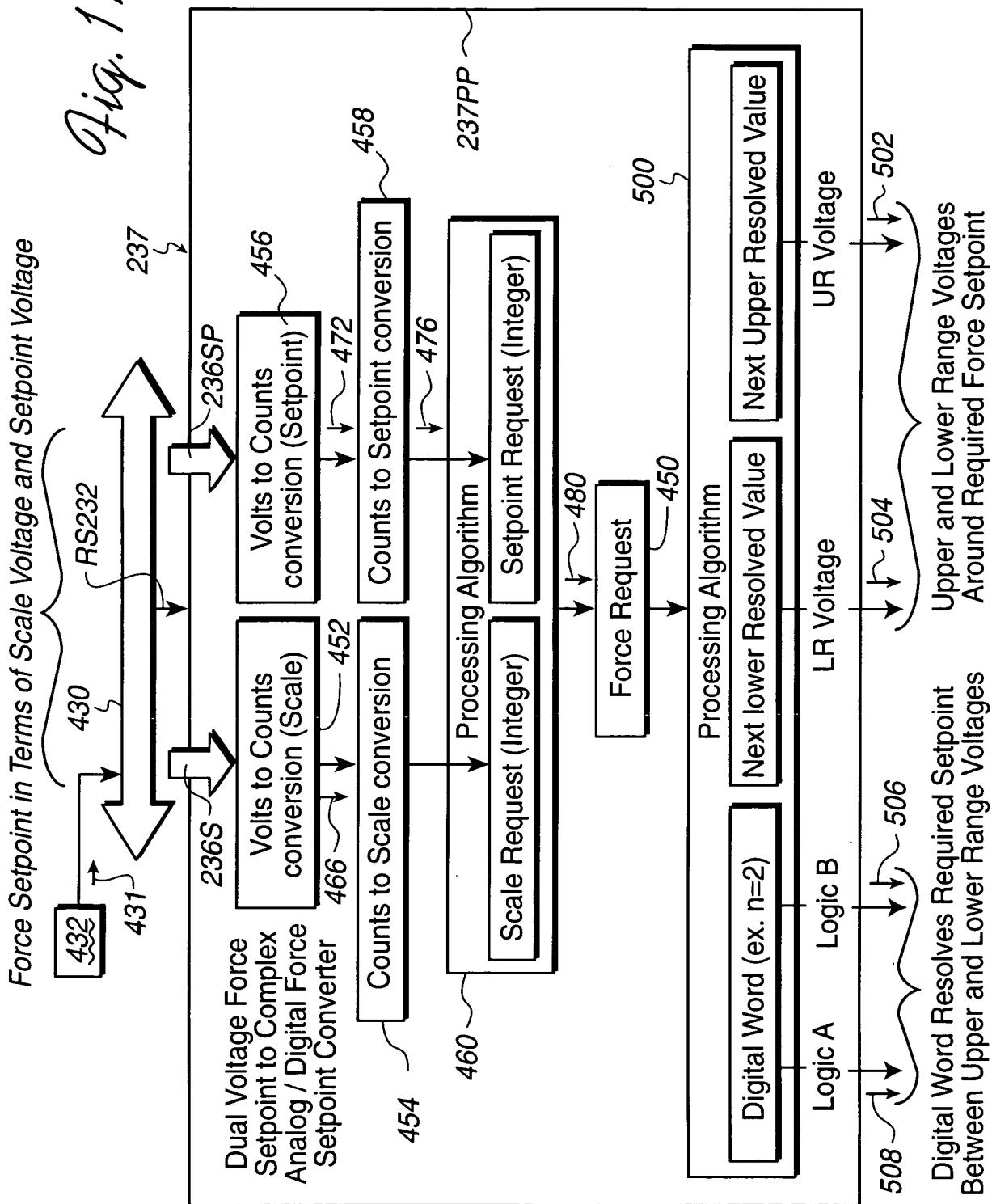
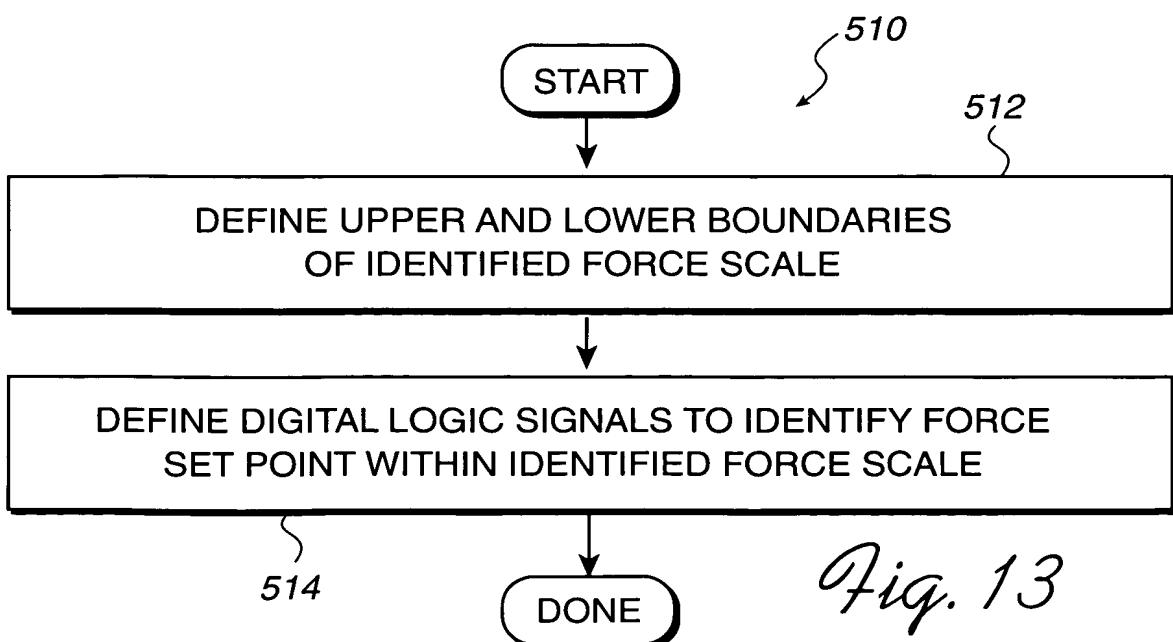
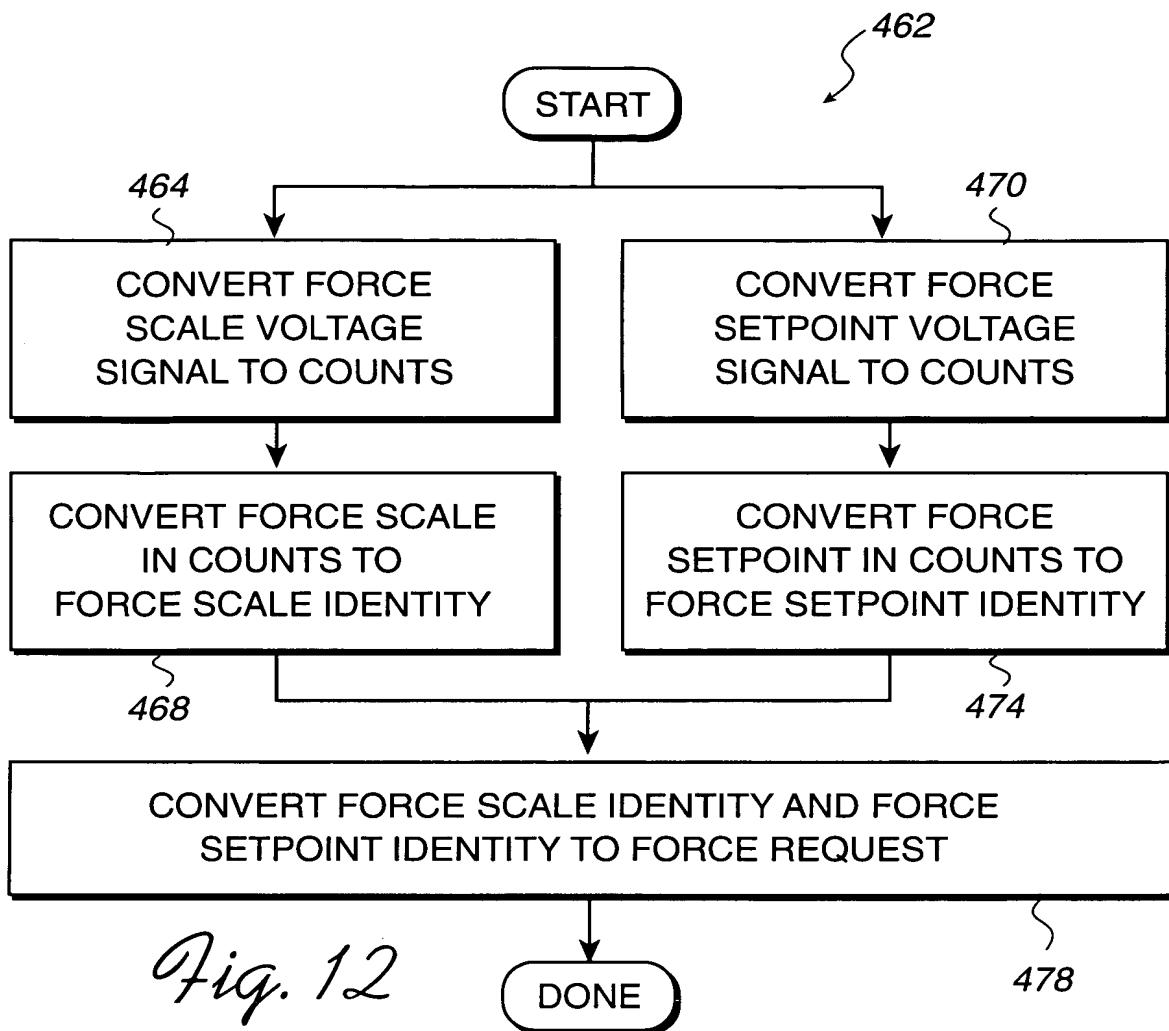


Fig. 10

**Title: METHODS WITH RESOLUTION ENHANCEMENT FEATURE FOR
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Fig. 11





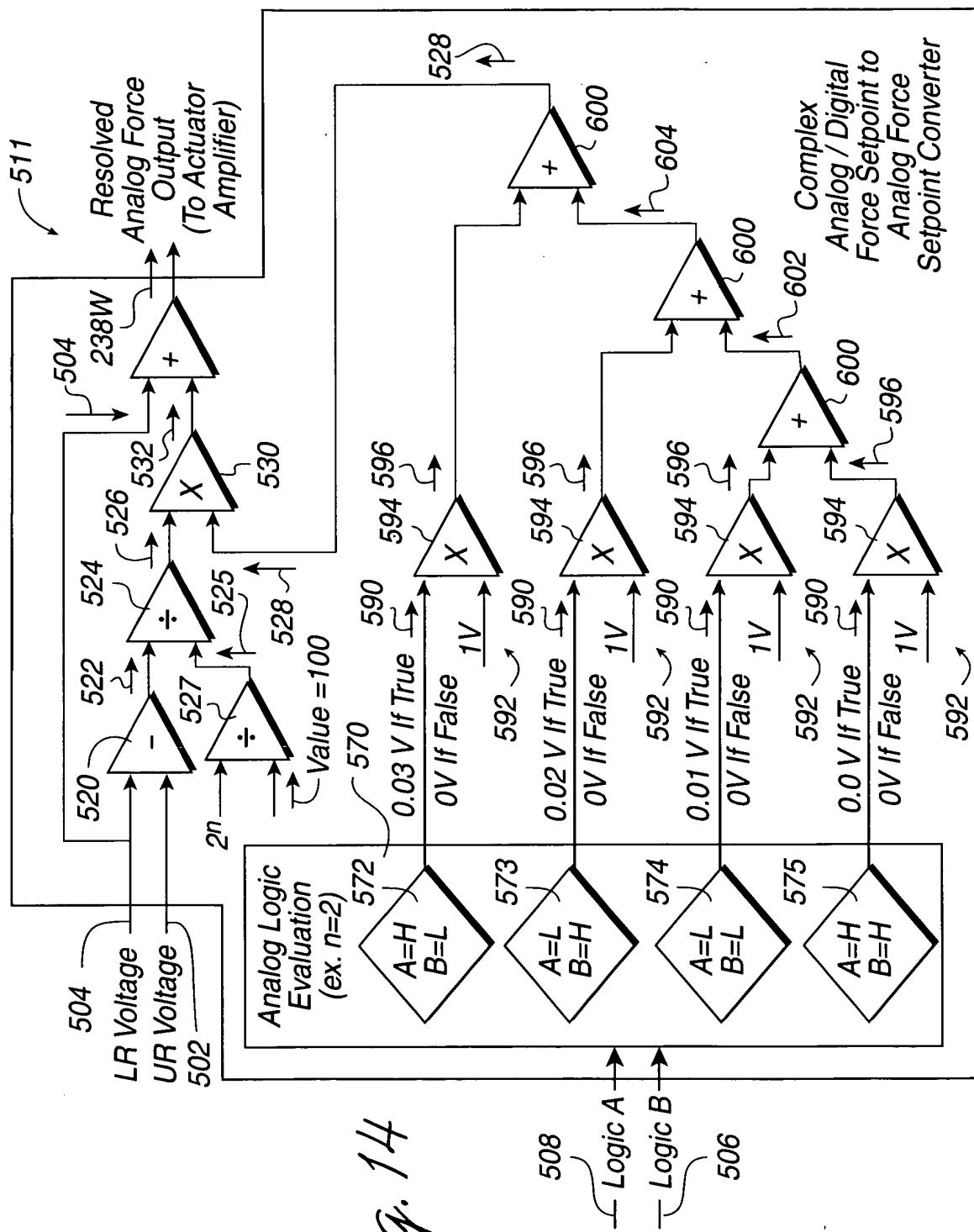


Fig. 14

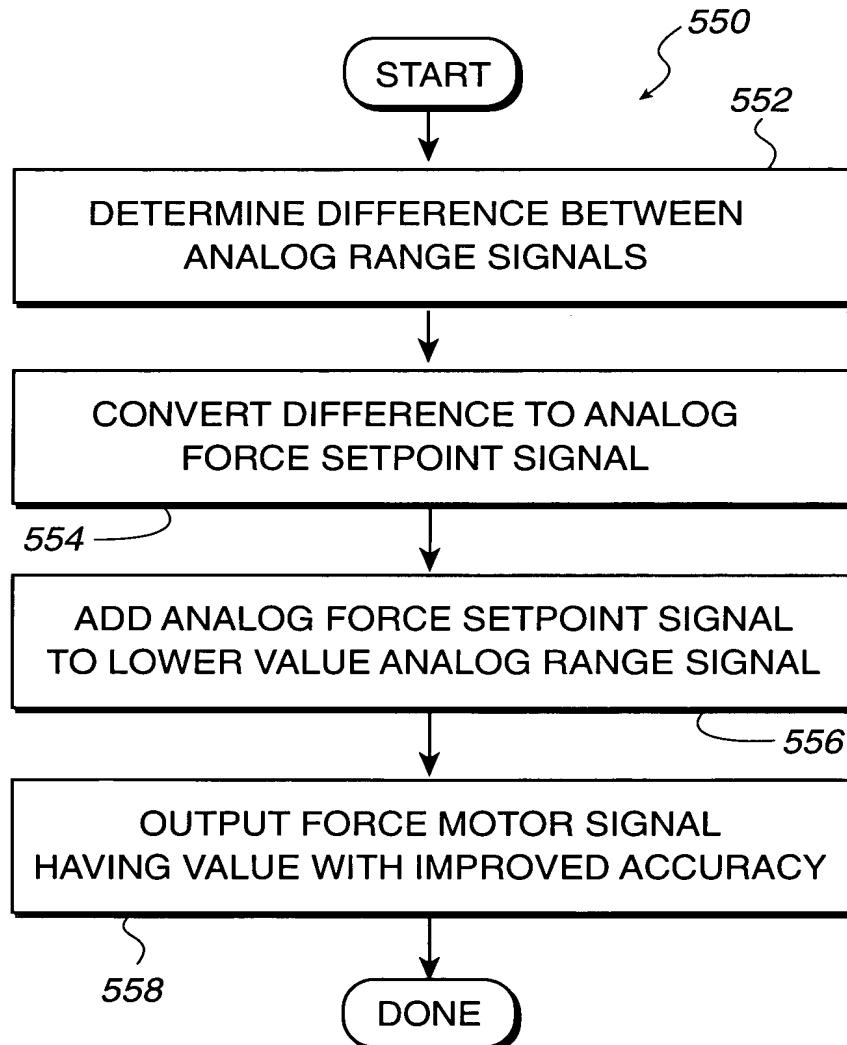


Fig. 15